

C2225C563MDRACTU

Specifications

Insulation Resistance

Aliases (C2225C563MDRAC7800) SMD Comm X7R HV, Ceramic, 0.056 uF, 20%, 1,000 VDC, X7R, SMD, MLCC, High Voltage, Temperature Stable, 2225, 3.2 mm



General Information	
Series	SMD Comm X7R HV
Style	SMD Chip
Description	SMD, MLCC, High Voltage, Temperature Stable
Features	High Voltage
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	430 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	2225
L	5.6mm +/-0.4mm
W	6.4mm +/-0.4mm
Т	1.6mm +/-0.20mm
S	3.2mm MIN
В	0.6mm +/-0.35mm
В	0.6mm +/-0.35mm

Capacitance	0.056 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	1000 VDC
Dielectric Withstanding Voltage	1,200 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0 Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours

17.8571 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

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